

BC848 series

30 V, 100 mA NPN general-purpose transistors

Rev. 07 — 17 November 2009

Product data sheet

1. Product profile

1.1 General description

NPN general-purpose transistors in Surface Mounted Device (SMD) plastic packages.

Table 1. Product overview

Type number	Package			PNP complement
	NXP	JEITA	JEDEC	
BC848B	SOT23	-	TO-236AB	BC858B
BC848W	SOT323	SC-70	-	BC858W

1.2 Features

- General-purpose transistors
- SMD plastic packages

1.3 Applications

- General-purpose switching and amplification

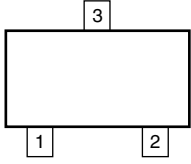
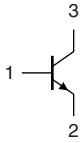
1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage	open base	-	-	30	V
I_C	collector current		-	-	100	mA
h_{FE}	DC current gain	$V_{CE} = 5\text{ V};$ $I_C = 2\text{ mA}$				
	BC848B		200	290	450	
	BC848W		110	-	800	

2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Symbol
1	base	 <p>006aaa144</p>	 <p>sym021</p>
2	emitter		
3	collector		

3. Ordering information

Table 4. Ordering information

Type number	Package		
	Name	Description	Version
BC848B	-	plastic surface mounted package; 3 leads	SOT23
BC848W	SC-70	plastic surface mounted package; 3 leads	SOT323

4. Marking

Table 5. Marking codes

Type number	Marking code ^[1]
BC848B	1K*
BC848W	1M*

- [1] * = -: made in Hong Kong
 * = p: made in Hong Kong
 * = t: made in Malaysia
 * = W: made in China

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter	-	30	V
V_{CEO}	collector-emitter voltage	open base	-	30	V
V_{EBO}	emitter-base voltage	open collector	-	5	V
I_C	collector current		-	100	mA
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms	-	200	mA
I_{BM}	peak base current	single pulse; $t_p \leq 1$ ms	-	200	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1]		
	SOT23		-	250	mW
	SOT323		-	200	mW
T_j	junction temperature		-	150	°C
T_{amb}	ambient temperature		-65	+150	°C
T_{stg}	storage temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]			
	SOT23		-	-	500	K/W
	SOT323		-	-	625	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

7. Characteristics

Table 8. Characteristics

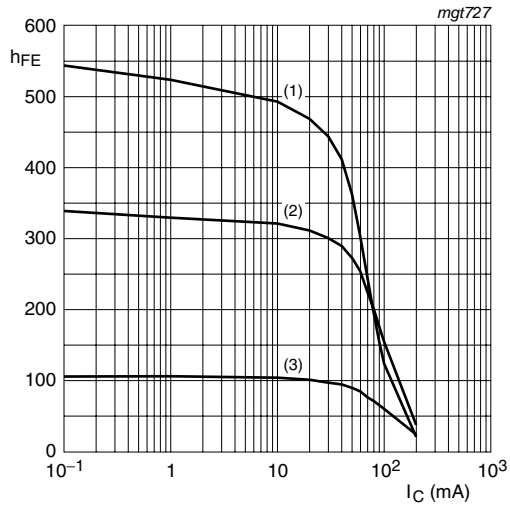
$T_{amb} = 25\text{ °C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
I_{CBO}	collector-base cut-off current	$V_{CB} = 30\text{ V}; I_E = 0\text{ A}$	-	-	15	nA	
		$V_{CB} = 30\text{ V}; I_E = 0\text{ A}; T_j = 150\text{ °C}$	-	-	5	μA	
I_{EBO}	emitter-base cut-off current	$V_{EB} = 5\text{ V}; I_E = 0\text{ A}$	-	-	100	nA	
h_{FE}	DC current gain	$V_{CE} = 5\text{ V}; I_C = 10\text{ }\mu\text{A}$	-	150	-		
		$V_{CE} = 5\text{ V}; I_C = 2\text{ mA}$					
		BC848B	200	290	450		
		BC848W	110	-	800		
V_{CEsat}	collector-emitter saturation voltage	$I_C = 10\text{ mA}; I_B = 0.5\text{ mA}$	-	90	250	mV	
		$I_C = 100\text{ mA}; I_B = 5\text{ mA}$	[1]	-	200	600	mV
V_{BEsat}	base-emitter saturation voltage	$I_C = 10\text{ mA}; I_B = 0.5\text{ mA}$	[2]	-	700	-	mV
		$I_C = 100\text{ mA}; I_B = 5\text{ mA}$	[2]	-	900	-	mV
V_{BE}	base-emitter voltage	$I_C = 2\text{ mA}; V_{CE} = 5\text{ V}$	[3]	580	660	700	mV
		$I_C = 10\text{ mA}; V_{CE} = 5\text{ V}$	[3]	-	-	770	mV
f_T	transition frequency	$V_{CE} = 5\text{ V}; I_C = 10\text{ mA}; f = 100\text{ MHz}$	100	-	-	MHz	
C_C	collector capacitance	$V_{CB} = 10\text{ V}; I_E = i_e = 0\text{ A}; f = 1\text{ MHz}$	-	2.5	3	pF	
NF	noise figure	$V_{CE} = 5\text{ V}; I_C = 200\text{ }\mu\text{A}; R_S = 2\text{ k}\Omega; f = 1\text{ kHz}; B = 200\text{ Hz}$	-	2	10	dB	

[1] Pulse test: $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$.

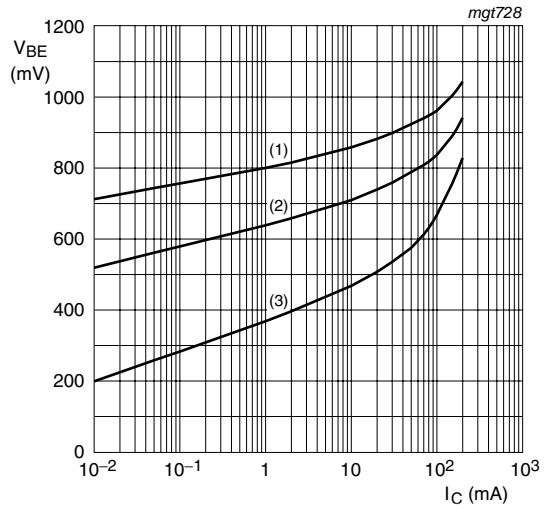
[2] V_{BEsat} decreases by approximately 1.7 mV/K with increasing temperature.

[3] V_{BE} decreases by approximately 2 mV/K with increasing temperature.



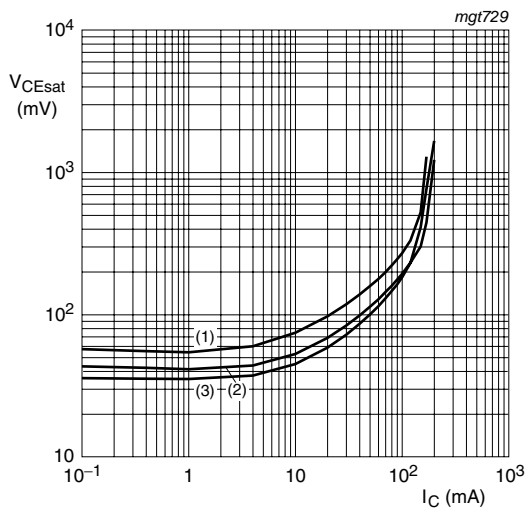
$V_{CE} = 5\text{ V}$
 (1) $T_{amb} = 150\text{ }^{\circ}\text{C}$
 (2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
 (3) $T_{amb} = -55\text{ }^{\circ}\text{C}$

Fig 1. BC848B: DC current gain as a function of collector current; typical values



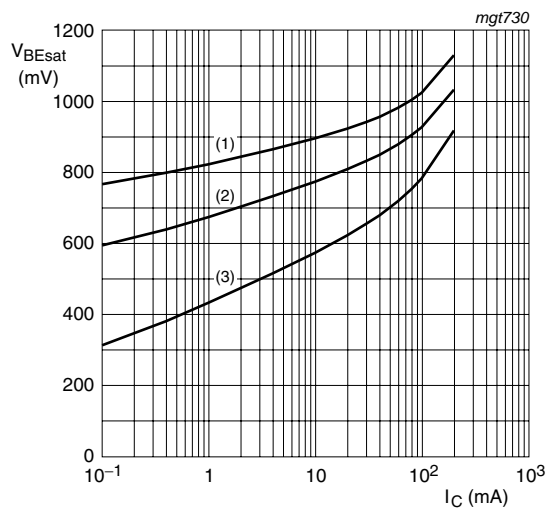
$V_{CE} = 5\text{ V}$
 (1) $T_{amb} = -55\text{ }^{\circ}\text{C}$
 (2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
 (3) $T_{amb} = 150\text{ }^{\circ}\text{C}$

Fig 2. BC848B: Base-emitter voltage as a function of collector current; typical values



$I_C/I_B = 20$
 (1) $T_{amb} = 150\text{ }^{\circ}\text{C}$
 (2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
 (3) $T_{amb} = -55\text{ }^{\circ}\text{C}$

Fig 3. BC848B: Collector-emitter saturation voltage as a function of collector current; typical values



$I_C/I_B = 10$
 (1) $T_{amb} = -55\text{ }^{\circ}\text{C}$
 (2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
 (3) $T_{amb} = 150\text{ }^{\circ}\text{C}$

Fig 4. BC848B: Base-emitter saturation voltage as a function of collector current; typical values

8. Package outline

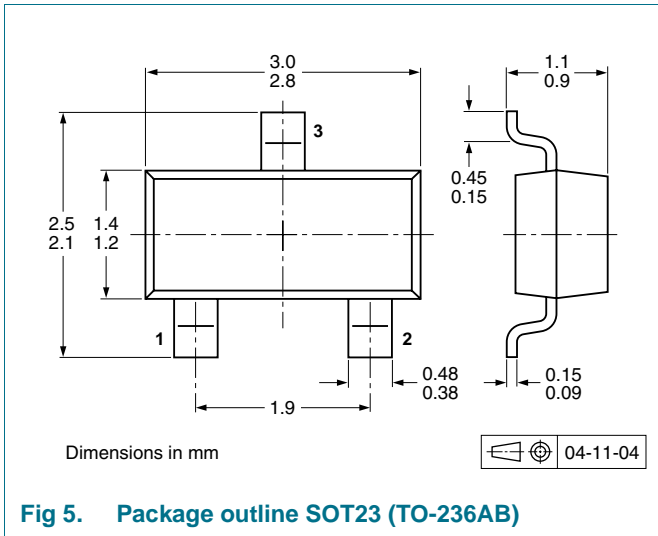


Fig 5. Package outline SOT23 (TO-236AB)

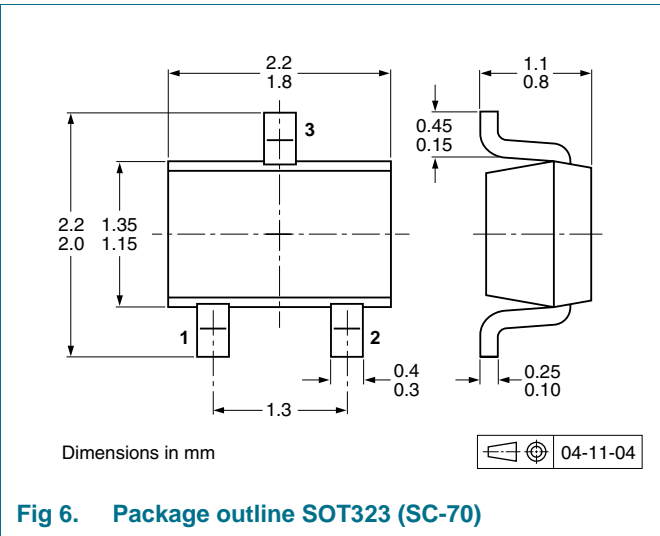


Fig 6. Package outline SOT323 (SC-70)

9. Packing information

Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity	
			3000	10000
BC848B	SOT23	4 mm pitch, 8 mm tape and reel	-215	-235
BC848W	SOT323	4 mm pitch, 8 mm tape and reel	-115	-135

[1] For further information and the availability of packing methods, see [Section 14](#).

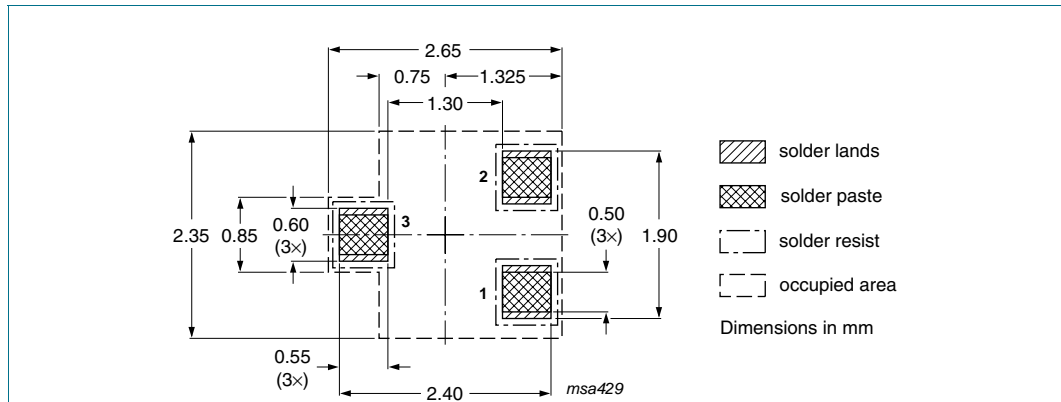


Fig 9. Reflow soldering footprint SOT323 (SC-70)

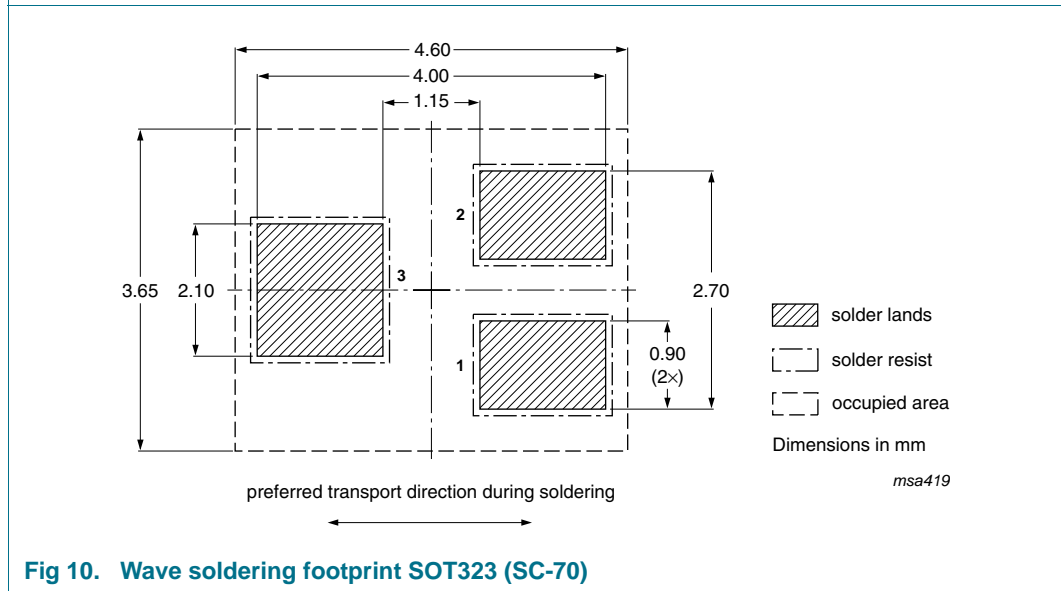
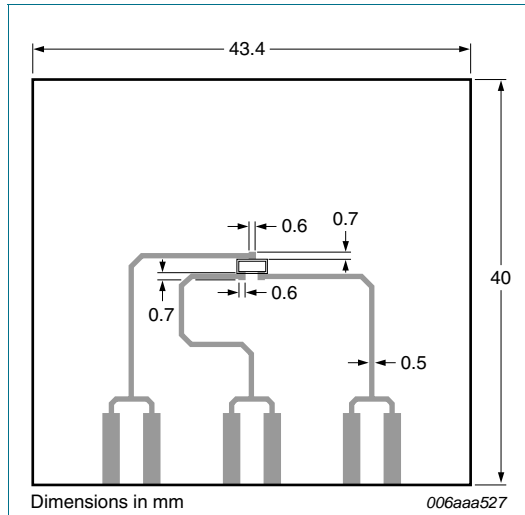


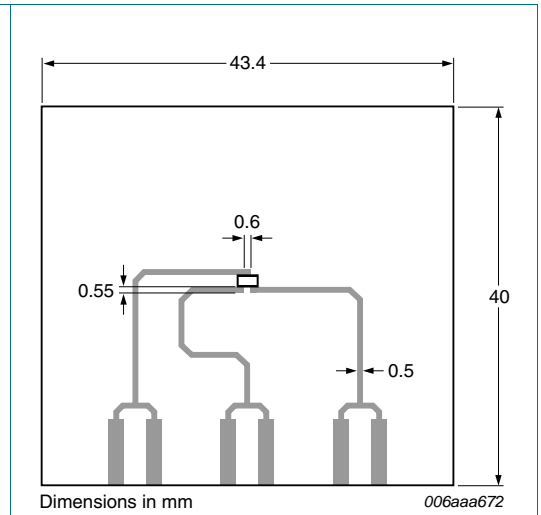
Fig 10. Wave soldering footprint SOT323 (SC-70)

11. Mounting



PCB thickness:
FR4 PCB = 1.6 mm

Fig 11. FR4 PCB, standard footprint SOT23 (TO-236AB)



PCB thickness:
FR4 PCB = 1.6 mm

Fig 12. FR4 PCB, standard footprint SOT323 (SC-70)

12. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BC848_SER_7	20091117	Product data sheet	-	BC848_SER_6
Modifications:	<ul style="list-style-type: none"> This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content. Figure 9 "Reflow soldering footprint SOT323 (SC-70)": updated Figure 10 "Wave soldering footprint SOT323 (SC-70)": updated 			
BC848_SER_6	20060203	Product data sheet	-	BC846_BC847_ BC848_5 BC846W_BC847W_ BC848W_4
BC846_BC847_BC848_5	20040206	Product specification	-	BC846_BC847_ BC848_4
BC846W_BC847W_ BC848W_4	20020204	Product specification	-	BC846W_847W_3

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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Date of release: 17 November 2009

Document identifier: BC848_SER_7